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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM 10081796	FILING DATE 02/22/2002	CLASS 204	SUBCLASS 192.12	GAU 1753	EXAMINER McDonald
**APPLICANTS: Denning Dean; Garcia Sam; Smith Bradley; Loop Daniel; Hamilton Gregory; Islam Md.; Anthony Brian;					
**CONTINUING DATA VERIFIED: THIS APPLICATION IS A DIV OF 09/261,879 03/02/1999					
** FOREIGN APPLICATIONS VERIFIED: none					
PG-PUB		DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>	
Foreign priority claimed		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		ATTORNEY DOCKET NO	
35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no		SC91135A D01	
Verified and Acknowledged Examiners's initials		<i>[Signature]</i>			
TITLE : Method for forming a barrier layer for use in a copper interconnect					

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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